

ROBOTHERM

Robotics and Thermal Process Solution for Electronics Assembly,
Semiconductor Packaging and Engineered Products industries



MATERIAL HANDLING SYSTEM

WORHOLDER / INDEXER SERIES

Large Substrate Automatic Indexer Model*

APPLICATIONS

Large Substrate Auto-Indexing

- Wire Bonding
- Die Bonding
- Testing

OEM Equipements Upgrading

- Ball Bonder
- Wedge Bonder
- Die Bonder
- Die Attach Cure

STANDARD FEATURES* & BENEFITS

Worholder

- Handling system of the substrate
- Two mechanical clamps secure substrate
- Auto centering by pneumatic pistons
- X Axis stroke : up to 1000 mm (39,3 in)

Motorization

- **Handling system mounted on a linear motor**
- Programmable sequence

Electronic controller for following parameters

- Indexing sequences
- Index pitch
- Acceleration, speed, deceleration

Programs are downloaded from an external P.C

Acceleration : 0,01 à 2 G

Speed : up to 2 m/s

Stable and Reproducible process

Resolution 0,5 µm

Cleanroom Compatible

Optimal accessibility for service and maintenance

Durable low maintenance design for maximum "uptime"

Common European (CE) Product Safety Certification
SMEMA Compliant

* Special upon request

In Robotherm' s policy for continuous improvement, specifications can change without prior notice